



Final Product Change Notification

201610016F08 : Introduction of Quad Source for Leadless HVSON8 Product TJA1028TK/5V0/xx (xx=10 or 20)

Note: This notice is NXP Company Proprietary.



Issue Date: Jul 28, 2021 **Effective date:** Oct 26, 2021

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Management summary

Introduction of Quad Source for Leadless HVSON8 Product TJA1028TK/5V0/xx (xx=10 or 20)

Change Category

- Wafer Fab Process
- Assembly Process
- Product Marking
- Test Process
- Design
- Wafer Fab Materials
- Assembly Materials
- Mechanical Specification
- Test Equipment
- Errata
- Wafer Fab Location
- Assembly Location
- Packing/Shipping/Labeling
- Test Location
- Electrical spec./Test coverage
- Firmware
- Other

PCN Overview

Description

As part of the NXP Business Continuity Management (BCM) program NXP's Product Line In-Vehicle Networking (PL IVN) releases a quad-sourcing strategy for leadless HVSON8 package LIN transceiver products TJA1028TK/5V0/xx (xx=10 low slope, or 20 normal slope):

- For dual source product TJA1028TK/5V0/20/1 this implies the introduction of dual source back-end assembly, final test and packing/shipping/labeling (front-end waferfab diffusion is already dual source, as announced by NXP PL IVN PCN 20131011F04 from November 2013).

- For single source TJA1028TK/5V0/10 this implies the introduction of dual source front-end waferfab diffusion AND dual source back-end assembly, final test and packing/shipping/labeling
To this end, assembly, final test and packing/shipping/labelling of these products will start in a 2nd location ASEN, Suzhou, China, in parallel to the running production in site ATBK, Bangkok, Thailand. For the /10 product waferfab diffusion will start in a 2nd location SSMC, Singapore, next to the current waferfab ICN8, Nijmegen, the Netherlands. This continues NXP's Global BCM process to establish an industrial base that is agile, robust and can reliably service the long term forecasted market growth of IVN products.

Please note the following:

- Product TJA1028T in SO package has been quad sourced before, as announced by NXP PCN 201610016F01U01 from June 2017

- The 3V3 versions of leadless HVSON8 package product TJA1028TK (TJA1028TK/3V3/xx, xx=10 low slope, or 20 normal slope) will NOT be released quad source, and nothing changes. You however still receive this PCN to provide clarity/closure also for the leadless HVSON8 package 3V3 product versions
- Accepting this PCN does NOT resolve the short-term supply situation, but is advised to enable mid- to long-term capacity increase

Quad source means that a product can be:

- diffused in either waferfab ICN8, Nijmegen, the Netherlands or SSMC, Singapore
- assembled, final tested and packed/shipped/labeled in either assembly site ATBK, Bangkok, Thailand, or ASEN, Suzhou, China

The actual sourcing is at NXP's discretion.

This change does not affect the currently released NXP 12NC product part numbers for TJA1028TK. New 12NCs have been created to make use of the Quad Source.

In the attachment to this Product Change Notification (PCN) details of the changes involved are given, as well as seven additional documents:

- The AEC-Q100 qualification results for the release of ASEN assembly
- A release report for ASEN Final Test (FT)
- The AEC-Q100 qualification results for the release of SSMC diffusion for the /10 product version
- The applicable ZVEI Delta Qualification Matrices (DeQuMa, one for the diffusion dual source, one for the assembly dual source), both in zipped excel and pdf format

See the paragraphs 'Additional information' and 'Remarks' below for instructions on how to obtain these documents. Attached to this e-mail are two excel files. One contains the sales history for your affected part numbers, the other the product change list. In both files reference is made to new part number, orderable part number and NXP 12NC code. This is the NXP-advised new part in case you want to make use of the Quad Source.

Reason

NXP has the responsibility to have appropriate processes and procedures in place to ensure the ability to continue business operations in the event of an interruption affecting all or part(s) of the NXP organization. NXP has a Business Continuity Management (BCM) program in place since 2010. The BCM program includes 3 elements:

- 1. Risk Management per site
- 2. Contingency on Product level
- 3. Supplier Risk management.

This PCN refers to the 2nd element "Contingency on product level" which includes also the Quad Source option.

The second reason for creating a Quad Source is to establish an industrial base able to support the ever-increasing demand for NXP A-BCD3 products, driven by longer term growth in the In-Vehicle Networking market.

It has been decided to establish a Quad Source for product TJA1028TK/5V0/xx (xx=10 or 20). This means that this product, which is currently assembled, final tested and packed/shipped/labeled in ATBK, Bangkok, Thailand, will also be assembled, final tested and packed/shipped/labeled in ASEN, Suzhou, China, in parallel to ATBK. For the /10 product, which is currently diffused in ICN8, Nijmegen, the Netherlands, will also be diffused in SSMC, Singapore.

Identification of Affected Products

Top Side Marking

In the attachment to this PCN it is shown how the product name and the marking changes.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Aug 30, 2021

Anticipated Impact on Form, Fit, Function, Reliability or Quality

There is no impact to the product's functionality.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

The current products are not affected by this change. We will merely add a back-end assembly, final test and packing/shipping/labeling Dual Source, creating a true Quad Source under new NXP 12NC product part numbers.

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Aug 27, 2021.

Remarks

Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached document with relevant detailed information from the tab 'Files'.

Should you not be able to obtain this document, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

Related Notification

Notification	Issue Date	Effective Date	Title
201301011F04	Nov 17, 2013	Feb 15, 2014	Introduction of Dual Source for product TJA1028
201610016F01U01	Jun 03, 2017	Aug 30, 2017	Introduction of Quad Source for Product TJA1028

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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